

Mariappan Murugesan

List of Publications by Year in descending order

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#	ARTICLE	IF	CITATIONS
1	Low-temperature multichip-to-wafer 3D integration based on via-last TSV with OER-TEOS-CVD and microbump bonding without solder extrusion. , 2020, , .		2
2	Oxide-Oxide Thermocompression Direct Bonding Technologies with Capillary Self-Assembly for Multichip-to-Wafer Heterogeneous 3D System Integration. Micromachines, 2016, 7, 184.	2.9	17
3	Reconfigured-Wafer-to-Wafer 3-D Integration Using Parallel Self-Assembly of Chips With Cu-SnAg Microbumps and a Nonconductive Film. IEEE Transactions on Electron Devices, 2014, 61, 533-539.	3.0	41
4	Multichip-to-Wafer Three-Dimensional Integration Technology Using Chip Self-Assembly With Excimer Lamp Irradiation. IEEE Transactions on Electron Devices, 2012, 59, 2956-2963.	3.0	44
5	Multichip Self-Assembly Technology for Advanced Die-to-Wafer 3-D Integration to Precisely Align Known Good Dies in Batch Processing. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 1873-1884.	2.5	31
6	Self-Assembly of Chip-Size Components with Cavity Structures: High-Precision Alignment and Direct Bonding without Thermal Compression for Hetero Integration. Micromachines, 2011, 2, 49-68.	2.9	23